Method and apparatus for mounting semiconductor chips

ABSTRACT

An apparatus for mounting semiconductor chips has a dispensing station (1) configured to dispense adhesive portions to the substrate locations of a substrate, a bonding station (3) configured to place semiconductor chips on the substrate locations and a transport device (4) configured to transport the substrates along a transport path. The transport device (4) includes a buffer station (2) disposed between the dispensing station (1) and the bonding station (3). The buffer station (2) is configured to temporarily remove a substrate which is to be transported from the dispensing station (1) to the bonding station (3), or in reverse direction, from the transport path so that another substrate can be transported by the transport device (4) from the bonding station (3) to the dispensing station (1), or in reverse direction, respectively.

(Fig. 1)